

ABSTRACT

The present invention relates to a polishing apparatus and a polishing method. The polishing apparatus includes an operation controller (9) configured to control a pressure in each of a plurality of pressure chambers. The operation controller (9) is
5 configured to control the pressure in the pressure chamber of the polishing head (1) corresponding to a specific position so that a difference between a control target film thickness value and an average film thickness value of the entire substrate is reduced.

FIG. 1